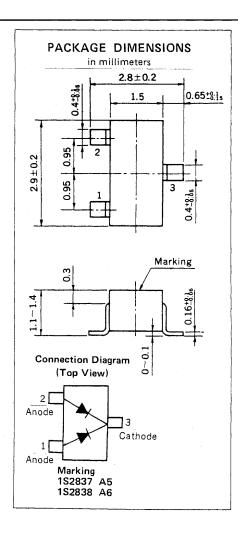


## SILICON SWITCHING DIODES

**1S2837,1S2838** 

# HIGH SPEED SWITCHING SILICON EPITAXIAL DOUBLE DIODES : COMMON CATHODE MINI MOLD



#### **FEATURES**

- Low capacitance: C<sub>t</sub> = 1.1 pF TYP.
- High speed switching:  $t_{rr} = 3.0 \text{ ns MAX}$ .
- Wide applications including switching, limitter, clipper.
- Double diode configuration assures economical use.

#### ABSOLUTE MAXIMUM RATINGS

Maximum Voltages and Currents ( $T_a = 25$  °C)

	1S2837	1\$2838	
$V_{RM}$	35	75	V
$V_R$	30	50	V
I <sub>FSM</sub>	6.0	6.0	Α
1 <sub>FSM</sub>	4.0	4.0	Α
I <sub>FM</sub>	450	450	mΑ
IFM	300	300	mΑ
Io	150	150	mΑ
10	100	100	mΑ
T <sub>j</sub>	125	125	°C
$T_{stg}$	-55 to +125	-55 to +125	°C
$R_{th(j-a)}$	1.0	1.0	°C/mW
$R_{th(j-a)}$	0.67	0.67	°C/mW
	VR IFSM IFSM IFM Io Io To Tstg  Rth(j-a)	VRM       35         VR       30         IFSM       6.0         IFSM       4.0         IFM       450         IFM       300         Io       150         Io       100          Tj       125         Tstg       -55 to +125         Rth (j-a)       1.0	$\begin{array}{cccccccccccccccccccccccccccccccccccc$

<sup>\*</sup> Both diodes loaded simultaneously.

## ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

CHARACTERISTIC	SYMBOL -	1S2837 (A5)		1S2838 (A6)			UNIT	TEST CONDITIONS	
		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	UNII	TEST CONDITIONS
Forward Voltage	VF1		0.67	1.0		0.67	1.0	V	IF = 10 mA
	V <sub>F2</sub>		0.75	1.1	-	0.75	. 1.1	V	IF = 50 mA
	VF3		0.85	1.2		0.85	1.2	V	IF = 100 mA
Reverse Current	l <sub>R</sub>			0.1				μА	V <sub>R</sub> = 30 V
	IR						0.1	μА	V <sub>R</sub> = 50 V
Capacitance	Ct		1.1	4.0		1.1	4.0	pF	V <sub>R</sub> = 0, f = 1.0 MHz
Reverse Recovery Time	t <sub>rr</sub>			3.0			3.0	ns	See Test Circuit.

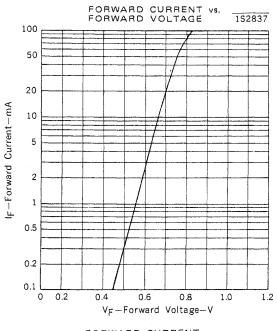
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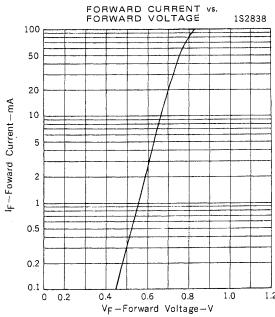
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

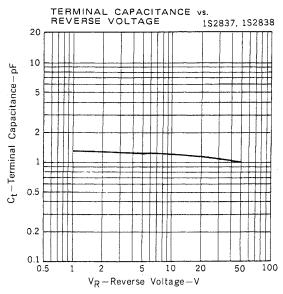
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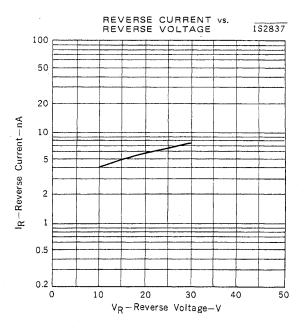
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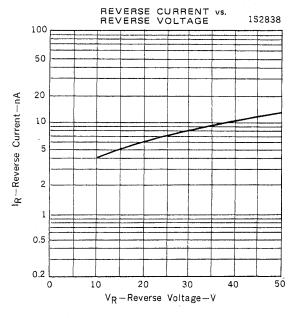
## TYPICAL CHARACTERISTICS (Ta = 25 °C)

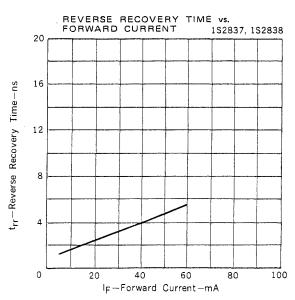




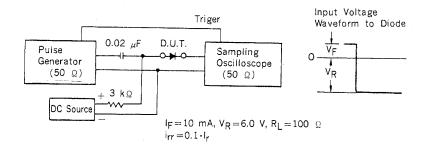


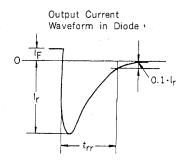






## REVERSE RECOVERY TIME (trr) TEST CIRCUIT





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